L Number	Hits	Search Text	DB	Time stamp
ı	1	5100737.pn. and tin	USPAT;	2003/08/03 13:21
		·	US-PGPUB	
-	518	361/709.ccls.	USPAT;	2003/07/29 10:48
			US-PGPUB	
-	2	176980.ap.	USPAT;	2003/07/29 10:47
			US-PGPUB	
-	1	361/709.ccls. and (graphite with lamellar)	USPAT;	2003/07/29 10:48
			US-PGPUB	
-	335	graphite with lamellar	USPAT;	2003/07/29 10:49
			US-PGPUB	
- ;	13	(graphite with lamellar) and (phase near2 change)	USPAT;	2003/07/29 10:49
			US-PGPUB	
-	2	(graphite with lamellar) and (phase adj change)	EPO; JPO;	2003/07/29 10:49
			DERWENT;	
			IBM_TDB	
-	257	graphite with lamellar	EPO; JPO;	2003/07/29 10:54
			DERWENT;	
			IBM_TDB	
-	0	428/40.1-42.3,343.ccls. and (heat adj sink)	EPO; JPO;	2003/07/29 10:55
			DERWENT;	
			IBM_TDB	
-	29	428/40.1-42.3,343.ccls. and (heat adj sink)	USPAT;	2003/08/01 12:40
	-^-		US-PGPUB	2002/07/20 16 22
-	707	(thermal adj interface) and (heat adj sink)	USPAT;	2003/07/29 16:23
			US-PGPUB	2002/07/20 16 11
-	137	((thermal adj interface) and (heat adj sink)) and (phase adj chang\$3)	USPAT;	2003/07/29 16:11
			US-PGPUB	2002/07/20 16 11
-	19	((((thermal adj interface) and (heat adj sink)) and (phase adj chang\$3))	USPAT;	2003/07/29 16:11
	24	and graphite) and (adhesive or wax)	US-PGPUB	2002/07/20 16:11
-	24	(((thermal adj interface) and (heat adj sink)) and (phase adj chang\$3)) and	USPAT;	2003/07/29 16:11
	99	graphite (thermal adjinterfees) and (heat adjinit)	US-PGPUB	2003/07/29 16:23
-	99	(thermal adj interface) and (heat adj sink)	EPO; JPO; DERWENT;	2003/07/29 10.23
			IBM TDB	
_	10	((thermal adj interface) and (heat adj sink)) and (phase adj change)	EPO; JPO;	2003/07/29 16:51
	10	((thermal adj interface) and (heat adj sink)) and (phase adj change)	DERWENT;	2003/07/27 10:51
			IBM_TDB	
_	455	(heat adj sink) and (adhesive with releas\$4)	USPAT;	2003/08/01 12:41
		(non any sint) and (deficience with release v)	US-PGPUB	2000,00,01
_	8	(heat adj sink) and (adhesive with releas\$4 with clean\$2)	USPAT;	2003/08/01 12:46
1	· ·	(1000 00) 000 (1000 00 000 00 000 00 000 00 00 00 00 00	US-PGPUB	
-	4	(heat adj sink) and (adhesive with releas\$4 with residue)	USPAT;	2003/08/01 12:49
1			US-PGPUB	
-	60	(heat adj sink) same (adhesive with releas\$4)	USPAT;	2003/08/01 12:52
			US-PGPUB	
-	3	(heat adj sink) and ((adhesive with (hot adj melt)) with residue)	USPAT;	2003/08/01 12:54
į			US-PGPUB	
-	46	((adhesive with (hot adj melt)) with residue)	USPAT;	2003/08/01 13:30
			US-PGPUB	
-	47	((adhesive with (hot adj melt)) with residue)	EPO; JPO;	2003/08/01 13:45
			DERWENT;	
			IBM_TDB	
-	13296	((adhesive with (hot adj melt)) withrepositionable)	EPO; JPO;	2003/08/01 13:45
			DERWENT;	
1			IBM_TDB	2002/08/01 12 1
-	1	((adhesive with (hot adj melt)) with repositionable)	EPO; JPO;	2003/08/01 13:45
			DERWENT;	
	22	((adhasina mish (hakadi mala)) mish assasida salah	IBM_TDB	2002/08/01 12:45
-	32	((adhesive with (hot adj melt)) with repositionable)	USPAT;	2003/08/01 13:47
1	^	(((allowing with (hot all moth)) and mount (1)) ((4)	US-PGPUB	2002/09/01 12 45
-	0	(((adhesive with (hot adj melt)) with removable)) and (thermal adj	USPAT;	2003/08/01 13:48
_	107	interface) ((adhesive with (hot adj melt)) with removable)	US-PGPUB	2002/08/01 12:49
-	107	((aunesive with (not auj men)) with removable)	USPAT; US-PGPUB	2003/08/01 13:48
		20.20 DM D 1	LO2-LOLOB	J

			LICDAT	2002/09/01 12 42
-	7	(((adhesive with (hot adj melt)) with removable)) and conductive	USPAT;	2003/08/01 13:49
	0.7		US-PGPUB	2002/00/01 12 50
-	87	(conductive with adhesive with (removable or repositionable))	USPAT;	2003/08/01 13:50
	_		US-PGPUB	2002/00/01 14 26
•	3	((conductive with adhesive with (removable or repositionable))) and (heat	USPAT;	2003/08/01 14:36
		adj sink)	US-PGPUB	2002/00/01 14 27
-	9	(heat adj sink) and (tin adj foil)	USPAT;	2003/08/01 14:37
	2.		US-PGPUB	2002/00/01 14 42
-	31	(heat adj sink) and (tin with graphite)	USPAT;	2003/08/01 14:42
		(h	US-PGPUB	2002/00/01 14 42
•	0	(heat adj sink) and (tin with graphite)	EPO; JPO;	2003/08/01 14:42
			DERWENT;	
			IBM_TDB	2002/00/01 14 42
-	1	(heat adj sink) and (tin same graphite)	EPO; JPO;	2003/08/01 14:42
			DERWENT;	
			IBM_TDB	2002/00/01 14 44
-	66	(heat adj sink) and (tin same graphite)	USPAT;	2003/08/01 14:44
	500	61 11 0 10	US-PGPUB	
-	792	(tin adj foil)	USPAT;	2003/08/01 14:44
			US-PGPUB	
-	3	((tin adj foil)) and (thermal adj interface)	USPAT;	2003/08/01 14:45
	100		US-PGPUB	
-	198	tin adj foil	EPO; JPO;	2003/08/01 14:45
			DERWENT;	
			IBM_TDB	
	1	(tin adj foil) and (thermal adj interface)	EPO; JPO;	2003/08/01 14:46
			DERWENT;	
			IBM_TDB	
•	4	(tin with foil) and ((thermal adj interface) or (heat adj sink))	EPO; JPO;	2003/08/01 14:47
			DERWENT;	
			IBM_TDB	
-	56	(tin with foil) and ((thermal adj interface) or (heat adj sink))	USPAT;	2003/08/01 14:47
			US-PGPUB	
-	8	((tin with foil) and ((thermal adj interface) or (heat adj sink))) and	USPAT;	2003/08/01 14:54
		graphite	US-PGPUB	2002/00/01 14 75
-	1	5100737.pn. and tin	USPAT;	2003/08/01 14:56
		6000404	US-PGPUB	
-	0	6090484.pn. and tin	USPAT;	2003/08/01 14:56
		(20000	US-PGPUB	000010010111
-	1	6372997.pn. and tin	USPAT;	2003/08/01 14:57
		772227	US-PGPUB	
-	0	5533256.pn. and tin	USPAT;	2003/08/01 14:57
		C49377077 141	US-PGPUB	2002/00/01 1:
-	0	6483707.pn. and tin	USPAT;	2003/08/01 14:57
		(200000	US-PGPUB	
-	0	6399209.pn. and tin	USPAT;	2003/08/03 13:21
	1		US-PGPUB	